

AF / 2811



Atty. Dkt. No. 039153-0457 (G1162)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Lopatin et al.

Title: METHOD OF USING TERNARY
COPPER ALLOY TO OBTAIN A
LOW RESISTANCE AND LARGE
GRAIN SIZE INTERCONNECT

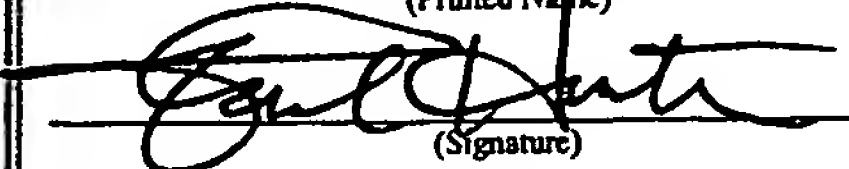
Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Ori Nadav

Art Unit: 2811

Confirmation Number: 7882

<p>CERTIFICATE OF MAILING</p> <p>I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below.</p> <p><u>Paul S. Hunter</u> (Printed Name)</p> <p><u></u> (Signature)</p> <p><u>August 4, 2006</u> (Date of Deposit)</p>

REPLY UNDER 37 CFR 1.116

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Examiner Nadav:

This communication is responsive to the Final Office Action dated June 26, 2006, concerning the above-referenced patent application.

Pending Claims are reflected in the listing of claims which begins on page 2 of this document.

Remarks/Arguments begin on page 6 of this document.

Please amend the application as follows:

ok to enter

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MADI_672435.1

O.N. 8/11/06